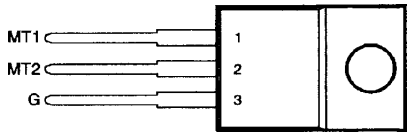
 APRIL 1971 - REVISED MARCH 1997

- **8 A RMS, 70 A Peak**
- **Glass Passivated Wafer**
- **400 V to 800 V Off-State Voltage**
- **Max I_{GT} of 50 mA (Quadrants 1 - 3)**

TO-220 PACKAGE
(TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDC2ACA

absolute maximum ratings over operating case temperature (unless otherwise *noted*)

RATING		SYMBOL	VALUE	UNIT
Repetitive peak off-state voltage (see Note 1)	TIC226D	V_{DRM}	400	V
	TIC226M		600	
	TIC226S		700	
	TIC226N		800	
Full-cycle RMS on-state current at (or below) 85°C case temperature (see Note 2)		$I_{T(RMS)}$	8	A
Peak on-state surge current full-sine-wave (see Note 3)		I_{TSM}	70	A
Peak on-state surge current half-sine-wave (see Note 4)		I_{TSM}	80	A
Peak gate current		I_{GM}	±1	A
Peak gate power dissipation at (or below) 85°C case temperature (pulse width ≤ 200 µs)		P_{GM}	2.2	W
Average gate power dissipation at (or below) 85°C case temperature (see Note 5)		$P_{G(AV)}$	0.9	W
Operating case temperature range		T_C	-40 to +110	°C
Storage temperature range		T_{stg}	-40 to +125	°C
Lead temperature 1.6 mm from case for 10 seconds		T_l	230	°C

NOTES: 1. These values apply bidirectionally for any value of resistance between the gate and Main Terminal 1.
2. This value applies for 50-Hz full-sine-wave Operation with resistive load. Above 85°C derate linearly to 110°C case temperature at the rate of 320 mA/°C.
3. This value applies for one 50-Hz full-sine-wave when the device is operating at (or below) the rated value of on-state current. Surge may be repeated after the device has returned to original thermal equilibrium. During the surge, gate control may be lost.
4. This value applies for one 50-Hz half-sine-wave when the device is operating at (or below) the rated value of on-state current. Surge may be repeated after the device has returned to original thermal equilibrium. During the surge, gate control may be lost.
5. This value applies for a maximum averaging time of 20 ms.

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
I_{DRM}	Repetitive peak off-state current	V_D = rated V_{DRM}	I_G = 0	T_C = 110°C			±2	mA
I_{GTM}	Peak gate trigger current	V_{supply} = +12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		2	50	mA
		V_{supply} = +12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		-12	-50	
		V_{supply} = -12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		-9	-50	
		V_{supply} = -12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		20		
V_{GTM}	Peak gate trigger voltage	V_{supply} = +12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		0.7	2	V
		V_{supply} = +12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		-0.8	-2	
		V_{supply} = -12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 µs		-0.8	-2	
		V_{supply} = -12 V†	R_L = 10 Ω	$t_{p(g)}$ > 20 ps		0.9	2	

† All voltages are with respect to Main Terminal 1

PRODUCT INFORMATION

Power INNOVATIONS

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electrical characteristics at 25°C case temperature (unless otherwise noted) (continued)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
V_{TM}	Peak on-state voltage	I_{TM} = ±12 A	I_G = 50 mA	(see Note 6)		±1.6	±2.1	V
I_H	Holding current	V_{supply} = +12 V†	I_G = 0	Init' I_{TM} = 100 mA		5	30	mA
		V_{supply} = -12 V†	I_G = 0	Init' I_{TM} = -100 mA		-9	-30	
I_L	Latching current	V_{supply} = +12 V†	(see Note 7)				50	mA
		V_{supply} = -12 V†					-50	
dv/dt	Critical rate of rise of off-state voltage	V_{DRM} = Rated V_{DRM}	I_G = 0	T_C = 110°C		±100		V/µs
$dv/dt_{(c)}$	Critical rise of commutation voltage	V_{DRM} = Rated V_{DRM}	I_{TRM} = ±12 A	T_C = 85°C	±5			V/µs

† All voltages are with respect to Main Terminal 1.

NOTES: 6. This Parameter must be measured using pulse techniques, $t_p \leq 1$ ms, duty cycle ≤ 2 %. Voltage-sensing contacts separate from the current carrying contacts are located within 3.2 mm from the device body.

7. The triacs are triggered by a 15-V (open-circuit amplitude) pulse supplied by a generator with the following characteristics: R_G = 100 Ω, $t_{p(g)}$ = 20 µs, t_r = ≤ 15 ns, f = 1 kHz.

thermal characteristics

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.8	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

TYPICAL CHARACTERISTICS

GATE TRIGGER CURRENT
VS
CASE TEMPERATURE

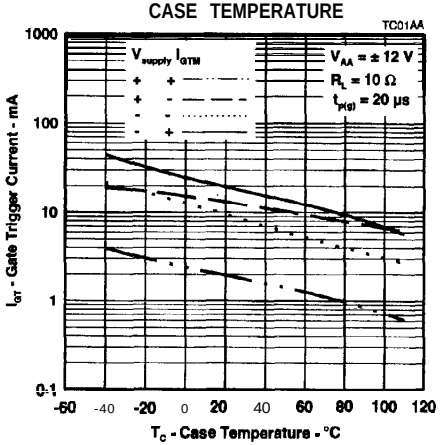


Figure 1.

GATE TRIGGER VOLTAGE
VS
CASETEMPERATURE

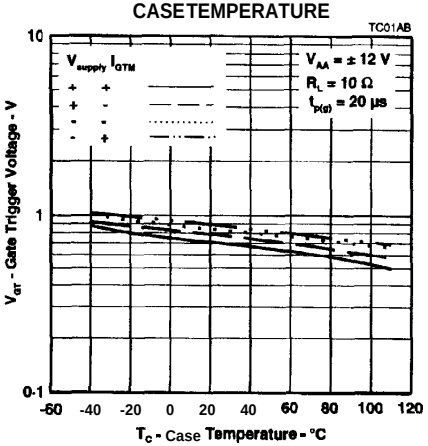


Figure 2.

PRODUCT INFORMATION

TYPICAL CHARACTERISTICS

HOLDING CURRENT
VS
CASE TEMPERATURE

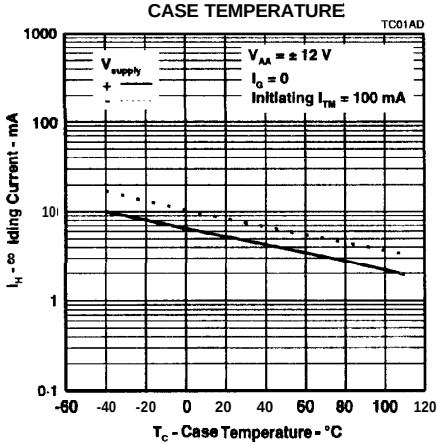


Figure 3.

GATE FORWARD VOLTAGE
VS
GATE FORWARD CURRENT

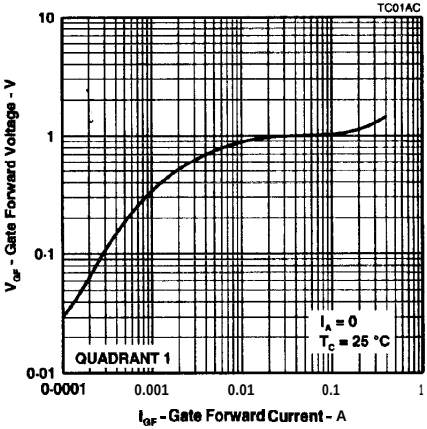


Figure 4.

LATCHING CURRENT
VS
CASE TEMPERATURE

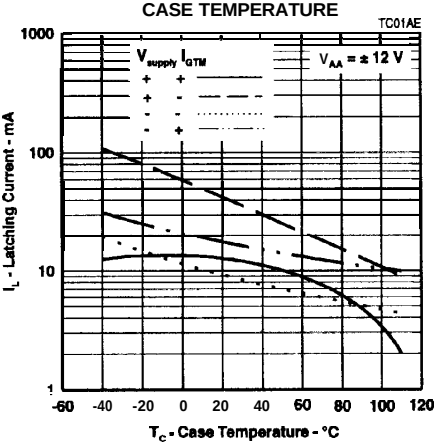


Figure 5.

SURGE ON-STATE CURRENT
VS
CYCLES OF CURRENT DURATION

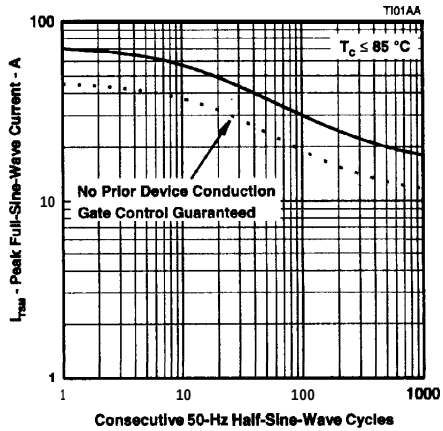


Figure 6.

TYPICAL CHARACTERISTICS

MAX RMS ON-STATE CURRENT
VS
CASE TEMPERIATURE

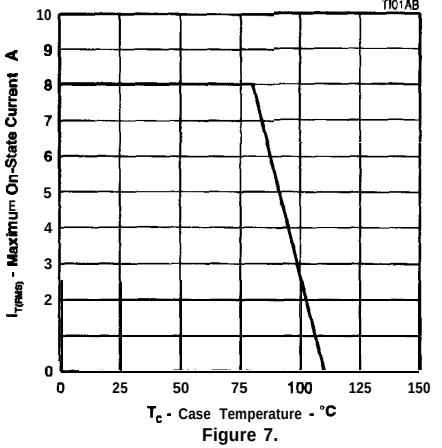


Figure 7.

MAX AVERAGE POWER DISSIPATED
VS
RMS ON-STATE CURRENT

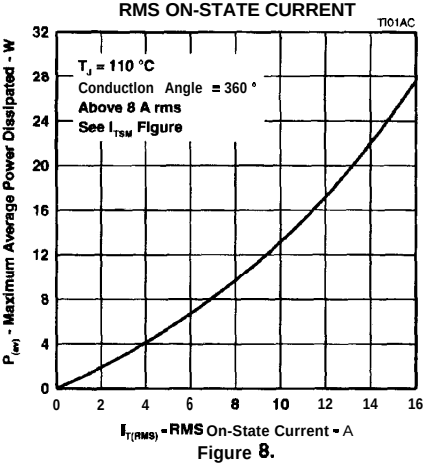
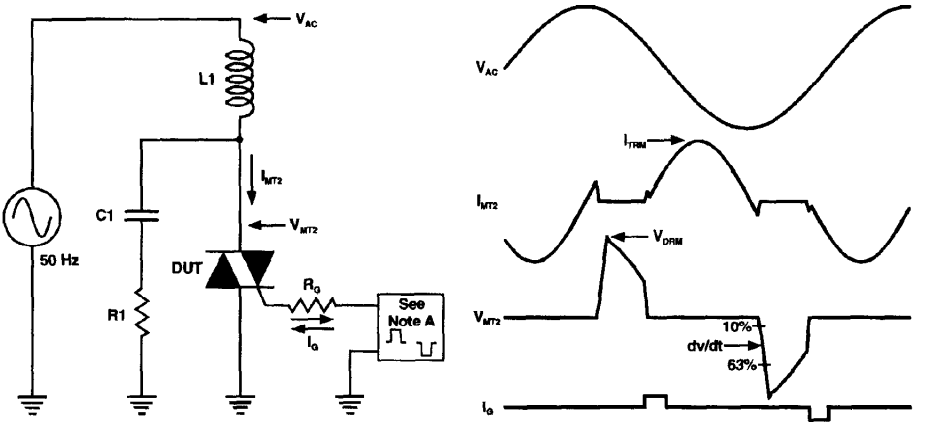


Figure 8.

PARAMETER MEASUREMENT INFORMATION



NOTE A: The gate-current pulse is furnishad by a trigger circuit which presents essentially an open circuit between pulses. The pulse is timed so that the off-state-voltage duration is approximately 800 ps.

PMC2AA

Figure 9.

GENERAL DESCRIPTION

Glass passivated triacs in a plastic envelope, intended for use in applications requiring high bidirectional transient and blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

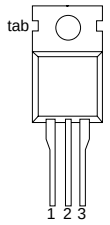
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
	BT139-	**500**	**600**	**800**	
	BT139-	**500F**	**600F**	**800F**	
	BT139-	**500G**	**600G**	**800G**	
V_{DRM}	Repetitive peak off-state voltages	500	600	800	V
$I_{T(RMS)}$	RMS on-state current	16	16	16	A
I_{TSM}	Non-repetitive peak on-state current	140	140	140	A

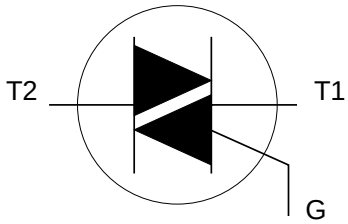
PINNING - TO220AB

PIN	DESCRIPTION
1	main terminal 1
2	main terminal 2
3	gate
tab	main terminal 2

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.			UNIT
				-500	**-600**	**-800**	
V_{DRM}	Repetitive peak off-state voltages		-	500[1]	600[1]	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 99$ ˚C	-	16			A
I_{TSM}	Non-repetitive peak on-state current	full sine wave; $T_j = 25$ ˚C prior to surge					
		t = 20 ms	-	140			A
		t = 16.7 ms	-	150			A
I^2t	I^2t for fusing	t = 10 ms	-	98			A^2s
dI_T/dt	Repetitive rate of rise of on-state current after triggering	I_{TM} = 20 A; I_G = 0.2 A; dI_G/dt = 0.2 A/µs					
		T2+ G+	-	50			A/µs
		T2+ G-	-	50			A/µs
		T2- G-	-	50			A/µs
		T2- G+	-	10			A/µs
I_{GM}	Peak gate current		-	2			A
V_{GM}	Peak gate voltage		-	5			V
P_{GM}	Peak gate power		-	5			W
$P_{G(AV)}$	Average gate power	over any 20 ms period	-	0.5			W
T_{stg}	Storage temperature		-40	150			˚C
T_j	Operating junction temperature		-	125			˚C

1 Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 A/µs.

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j\text{-}mb}$	Thermal resistance junction to mounting base	full cycle	-	-	1.2	K/W
		half cycle	-	-	1.7	K/W
$R_{th\ j\text{-}a}$	Thermal resistance junction to ambient	in free air	-	60	-	K/W

STATIC CHARACTERISTICS

T_j = 25 ˚C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.			UNIT
		BT139-			**...**	**...F**	**...G**	
I_{GT}	Gate trigger current	V_D = 12 V; I_T = 0.1 A						
		T2+ G+	-	5	35	25	50	mA
		T2+ G-	-	8	35	25	50	mA
		T2- G-	-	10	35	25	50	mA
		T2- G+	-	22	70	70	100	mA
I_L	Latching current	V_D = 12 V; I_{GT} = 0.1 A						
		T2+ G+	-	7	40	40	60	mA
		T2+ G-	-	20	60	60	90	mA
		T2- G-	-	8	40	40	60	mA
		T2- G+	-	10	60	60	90	mA
I_H	Holding current	V_D = 12 V; I_{GT} = 0.1 A	-	6	30	30	60	mA
V_T	On-state voltage	I_T = 20 A	-	1.2		1.6		V
V_{GT}	Gate trigger voltage	V_D = 12 V; I_T = 0.1 A	-	0.7		1.5		V
		V_D = 400 V; I_T = 0.1 A; T_j = 125 ˚C	0.25	0.4		-		V
I_D	Off-state leakage current	V_D = $V_{DRM(max)}$; T_j = 125 ˚C	-	0.1		0.5		mA

DYNAMIC CHARACTERISTICS

T_j = 25 ˚C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.			TYP.	MAX.	UNIT
		BT139-	**...**	**...F**	**...G**			
dV_D/dt	Critical rate of rise of off-state voltage	V_{DM} = 67% $V_{DRM(max)}$; T_j = 125 ˚C; exponential waveform; gate open circuit	100	50	200	250	-	V/µs
dV_{com}/dt	Critical rate of change of commutating voltage	V_{DM} = 400 V; T_j = 95 ˚C; $I_{T(RMS)}$ = 16 A; dI_{com}/dt = 7.2 A/ms; gate open circuit	-	-	10	20	-	V/µs
t_{gt}	Gate controlled turn-on time	I_{TM} = 20 A; V_D = $V_{DRM(max)}$; I_G = 0.1 A; dI_G/dt = 5 A/µs	-	-	-	2	-	µs

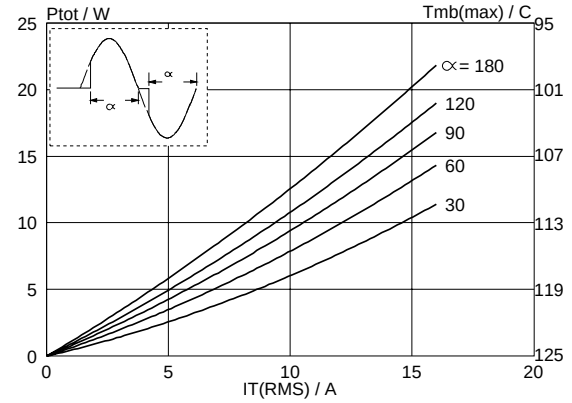


Fig.1. Maximum on-state dissipation, P_{tot}, versus rms on-state current, $I_{T(RMS)}$, where α = conduction angle.

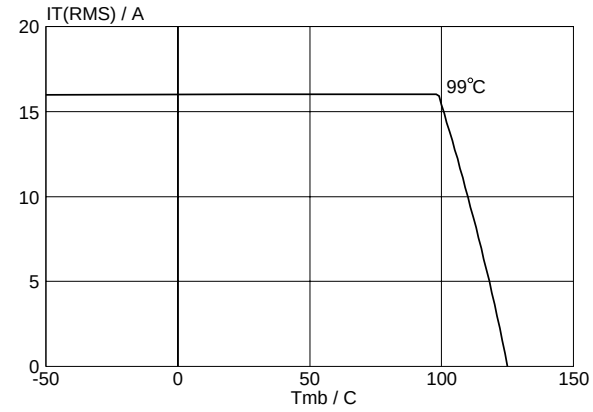


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb}.

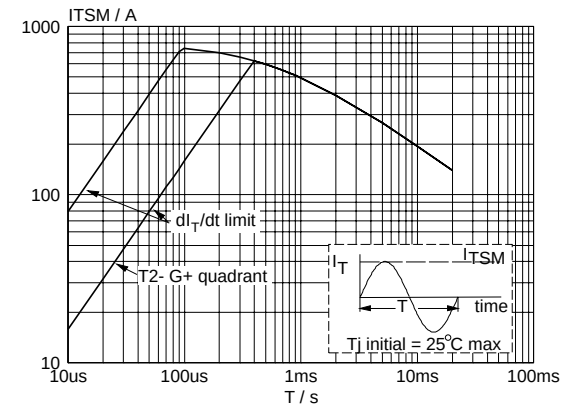


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM}, versus pulse width t_p, for sinusoidal currents, $t_p \leq 20ms$.

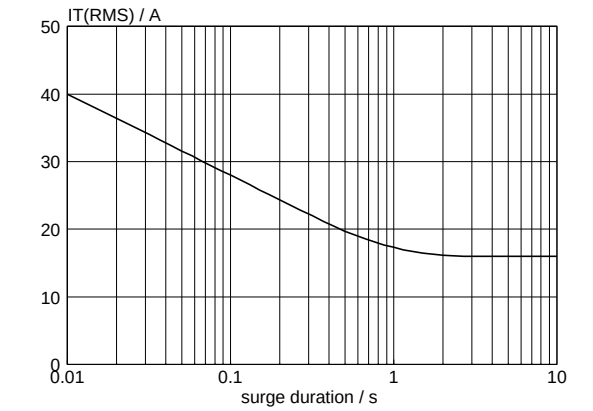


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{mb} \leq 99˚C$.

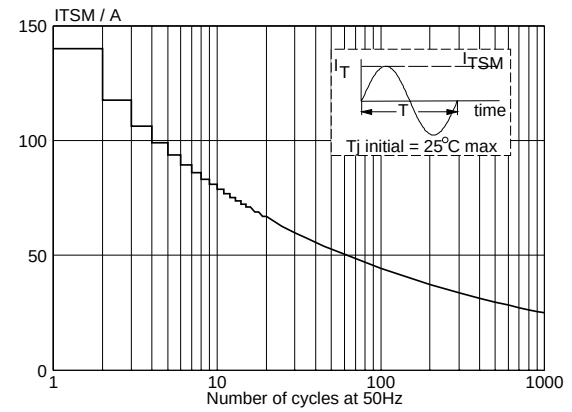


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM}, versus number of cycles, for sinusoidal currents, f = 50 Hz.

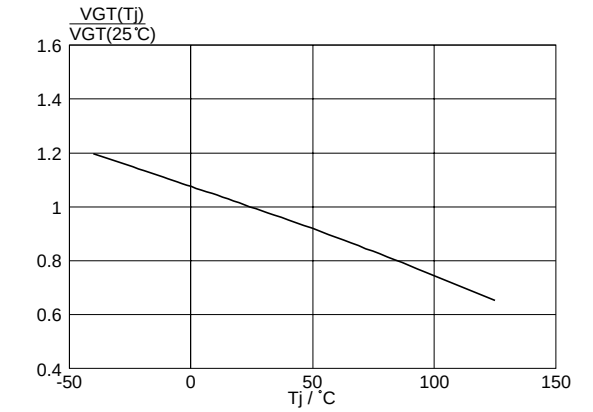


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/ V_{GT}(25˚C)$, versus junction temperature T_j.

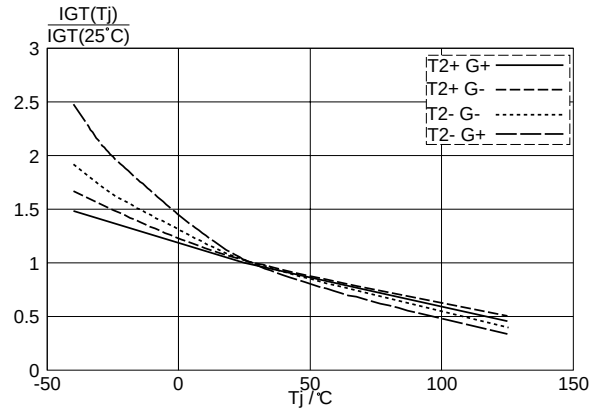


Fig.7. Normalised gate trigger current $I_{GT}(T_j)/ I_{GT}(25˚C)$, versus junction temperature T_j.

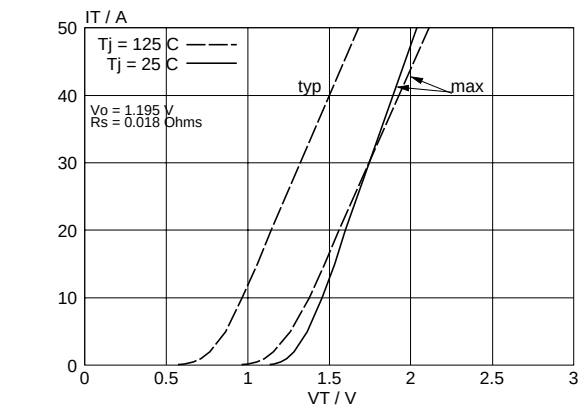


Fig.10. Typical and maximum on-state characteristic.

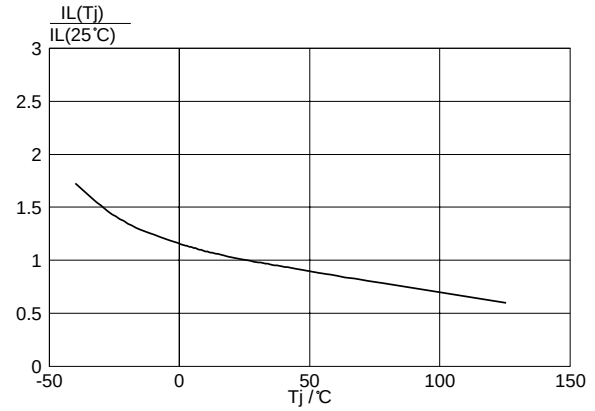


Fig.8. Normalised latching current $I_L(T_j)/ I_L(25˚C)$, versus junction temperature T_j.

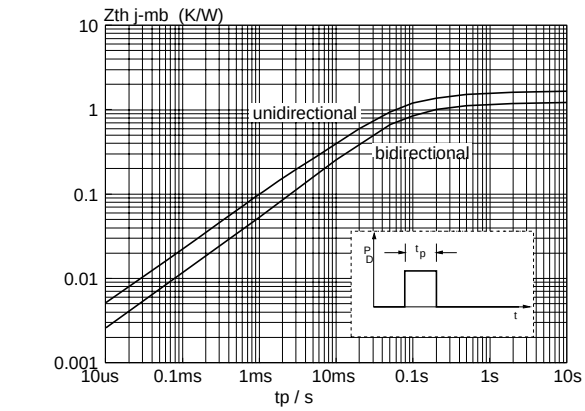


Fig.11. Transient thermal impedance $Z_{th\ j\text{-}mb}$, versus pulse width t_p.

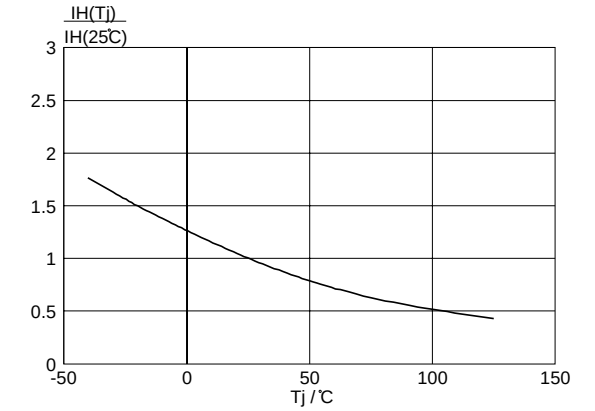


Fig.9. Normalised holding current $I_H(T_j)/ I_H(25˚C)$, versus junction temperature T_j.

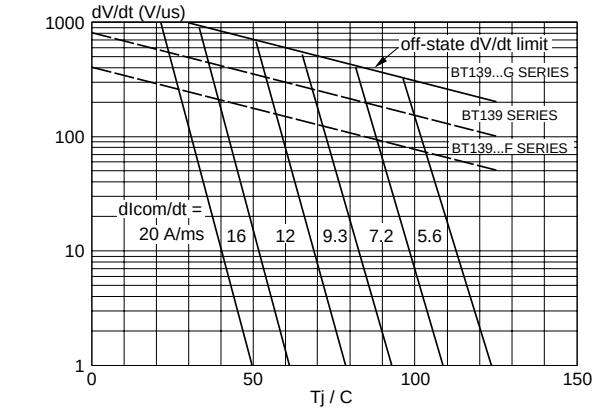


Fig.12. Typical commutation dV/dt versus junction temperature, parameter commutation dI_T/dt. The triac should commutate when the dV/dt is below the value on the appropriate curve for pre-commutation dI_T/dt.

MECHANICAL DATA

Dimensions in mm

Net Mass: 2 g

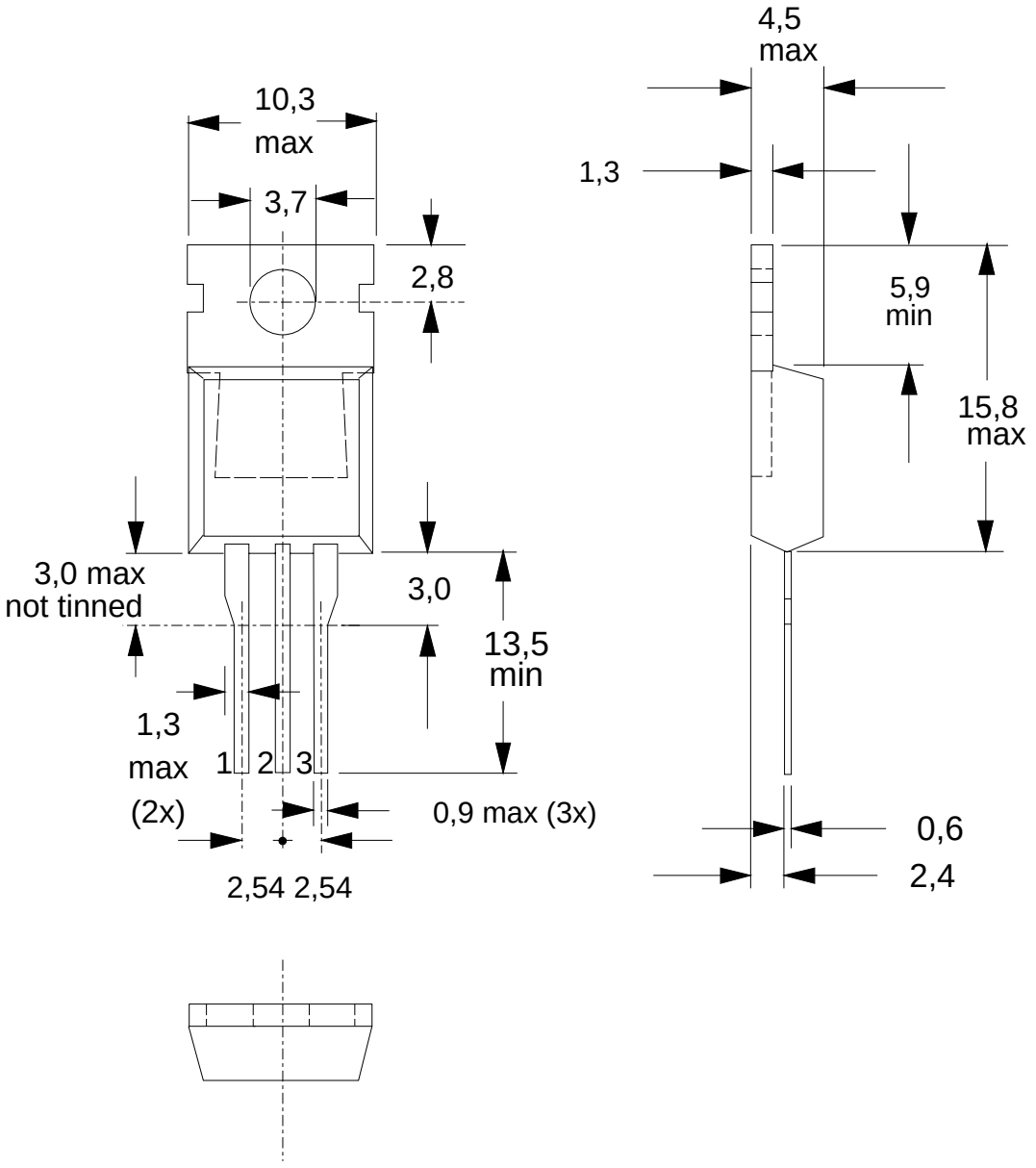


Fig.13. TO220AB; pin 2 connected to mounting base.

Notes
1. Refer to mounting instructions for TO220 envelopes.
2. Epoxy meets UL94 V0 at 1/8".

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.